MA27D27

Silicon epitaxial planar type

For super high speed switching

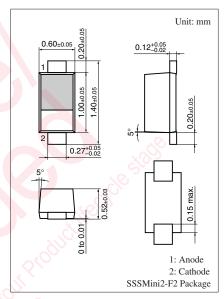
■ Features

- Small reverse current I_R
- Optimum for high frequency rectification because of its short reverse recovery time t_{rr}
- SSS-Mini type 2-pin package

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	20	V
Repetitive peak reverse voltage	V_{RRM}	20	V
Forward current (Average)	$I_{F(AV)}$	100	mA
Peak forward current	I_{FM}	200	mA
Non-repetitive peak forward surge current *	I_{FSM}	1	A
Junction temperature	T _j	150	°C
Storage temperature	T_{stg}	-55 to +150	°C,

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

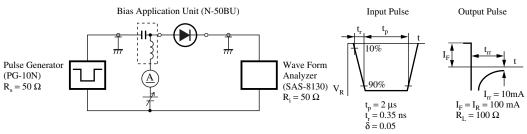


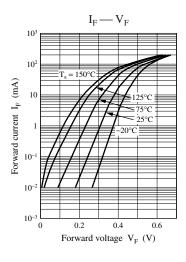
Marking Symbol: 8L

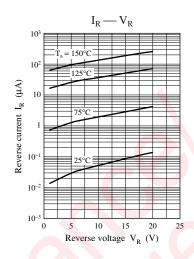
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

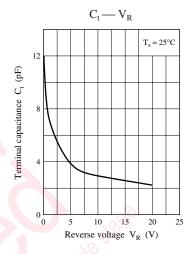
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _{F1}	$I_F = 10 \text{ mA}$	0	0.38	0.44	V
	V_{F2}	$I_F = 100 \text{ mA}$		0.54	0.58	
Reverse current	I_R	$V_R = 10 \text{ V}$	200		0.3	μΑ
Terminal capacitance	C _t	$V_R = 0 V, f = 1 MHz$		11		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}$		1		ns
		$I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$				

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. Rated input/output frequency: 250 MHz
 - 4. * : t_{rr} measurement circuit









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